

Harvatek Surface Mount PLCC LEDs Data Sheet T3A83UYG-60C000411U1930

Official Product	t HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	*******				
Specifications are subject notice. Proprietary data, dr	01/30/2024	Version 1.2	Page 1/15		



DISCLAIMER3	,
LIFE SUPPORT POLICY3	,
PRODUCT SPECIFICATIONS4	ļ
ATTENTION: ELECTROSTATIC DISCHARGE (ESD) PROTECTION4	
LABEL SPECIFICATIONS5	,
SPECIFICATIONS RANGE6)
PRODUCT FEATURES7	,
ELECTRO-OPTICAL CHARACTERISTICS7	,
PACKAGE OUTLINE DIMENSION AND RECOMMENDED SOLDERING PATTERN FOR REFLOW SOLDERING	10
7	,
ABSOLUTE MAXIMUM RATINGS7	,
CHARACTERISTICS OF T3A83UYG8	;
PRECAUTION FOR USE9)
PACKAGING 10)
Tape Dimension10)
REEL DIMENSION11	
Packing11	
Dry Pack12	
Baking12	<u>, </u>
PRECAUTIONS12	<u>.</u>
HANDLING OF SILICONE RESIN LEDS13	,
REFLOW SOLDERING14	ļ
REWORKING14	
CLEANING14	
CAUTIONS OF PICK AND PLACE15	;
REVISE HISTORY15	;

7					
Official Product	HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	*******				
Specifications are subject notice. Proprietary data, d	01/30/2024	Version 1.2	Page 2/15		



DISCLAIMER

HARVATEK reserves the right to make changes without further notice to any products herein to improve reliability, function or design. HARVATEK does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights, nor the rights of others.

Life Support Policy

HARVATEK's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of HARVATEK or HARVATEK INTERNATIONAL. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

7					
Official Product	HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	*******				
Specifications are subject notice. Proprietary data, dr	01/30/2024	Version 1.2	Page 3/15		



Product Specifications

Item	Specification	Material	Quantity
Luminous	UYG:71.5-180.0 mcd		
Intensity(Iv)	@20mA*3/ T_s = 25°C; Tolerance: ±10%		
Wavelength	UYG:564.5-576.5 nm		
	@20mA*3/ T _S = 25°C; Tolerance:±0.5nm		
Vf	UYG:1.6-2.6 V		
	@20mA*3/ T _S = 25°C ;Tolerance:±0.05V		
Ir	< 10 μA @ V _R = 5 V		
Resin	Clear	Silicon	
Carrier tape	EIA 481-1A specs	Conductive black tape	
Reel	EIA 481-1A specs	Conductive black	
Label	HT standard	Paper	
Packing bag	250x230mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	HT standard	Paper	Non-specified

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Note: This is shipped test conditions

*Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlGaInP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must

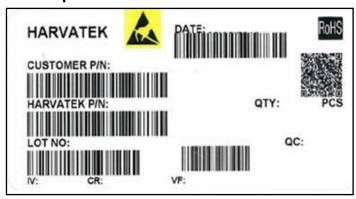
be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Official Product	HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	*******				
Specifications are subject notice. Proprietary data, dr	01/30/2024	Version 1.2	Page 4/15		



Label Specifications



■Harvatek P/N:

T 3A8 3 UYG- 60C- 0004 11

Product	Package	Dice Qty	Color	Current	Series Number	Taping
LF	5.4(L)x5.0(W)x1.6(H) mm	3.Tri	UYG: Ultra Bright	60mA	X001~XZZZ	1.Taping style
			Yellow Green			2. Qty

■ Lot No.:

1 2	3	4	5	6	7	8	9	10
E 1	Α	1	Α	2	2	L	1	2
Code 1 2	Code 3	Code 4	Code 5	Code 6	Code 7	Code 8	Code 9	Code 10
	Mfg. Year	Mfg. Month	Mfg. Date	Consecuti	ve number		Special code	:
Internal Tracing Code	2020-L 2021-M 2022-P 2023-Q 2026-T 2027-V 2030-Y 2031-Z	1:Jan. 2:Feb. A:Oct. B:Nov. C:Dec.	1:A 2:B 3:C 26:Z 27:7 28:8 29:9 30:3 31:4	01-	-ZZ		000-ZZZ	

Official Product	HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	*******				
Specifications are subject notice. Proprietary data, dr	01/30/2024	Version 1.2	Page 5/15		



Specifications Range

■Luminous Intensity (Iv) Bin:

Color	Bin Code	Spec. Range
UYG	Q	71.5-112.5 mcd
	R	112.5-180.0 mcd

Note: It maintains a tolerance of ±10% on Luminous Intensity

■Wavelength Bin:

Color	Bin Code	Spec. Range
	В	564.5-567.5 nm
111/0	С	567.5-570.5 nm
UYG	D	570.0-573.5 nm
	E	573.5-576.5 nm

Note: It maintains a tolerance of ±0.5nm on Wavelength Bin

■Forward Voltage (Vf) Bin:

Color	Bin Code	Spec. Range
UYG	E1A	1.6-2.6 V

Note: It maintains a tolerance of ±0.05V on forward voltage measurements

Official Product	oduct HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	*******	* *********			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		01/30/2024	Version 1.2	Page 6/15	



Product Features

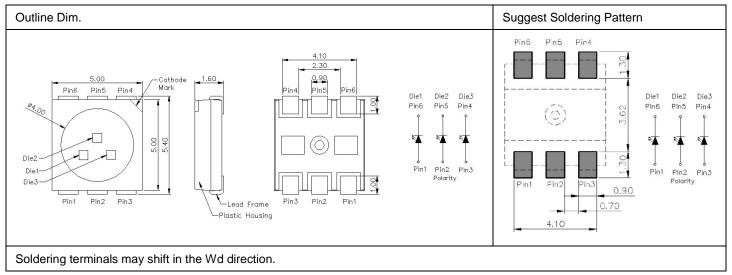
Electro-Optical Characteristics

				•					(I _{Solo}	dering , 25 °C)
					(V)	Wa	ivelength λ	(nm)	I _∨ (mcd)	Viewing
	Series	Emitting Color	Material	typ	max	λ_{D}	λ_{P}	Δλ	Typical	Angle $2\theta \frac{1}{2}$
	T3A83UYG	UYG	GaP	2.2	2.6	573	568	30	112.5	120

Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering

(Unit:mm Tolerance: +/-0.1)

05 00)



Absolute Maximum Ratings

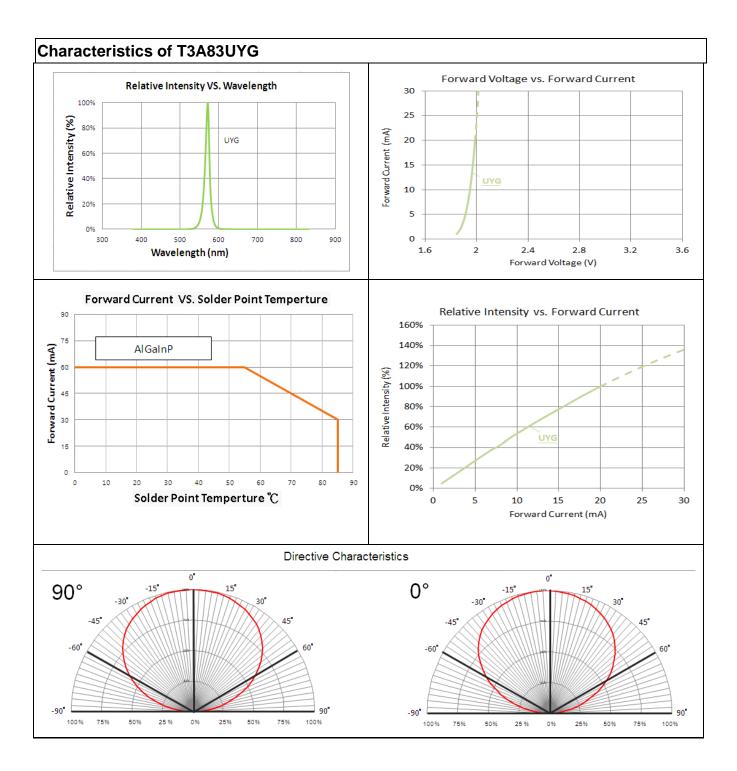
(T_{Soldering} 25 °C)

Series	P _D (mW)	I _F (mA)	I _{FP} (mA)*	T _{OP} (°C)	T _{ST} (°C)
Color	Power Dissipation Forward Current		Pulse Forward	Operating	Storage
Color	Power Dissipation	Forward Current	Current	Temperature	Temperature
UYG	156	60	100	-40~+85	-40~+100

^{*} Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width

Official Product	HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	********	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		01/30/2024	Version 1.2	Page 7/15	





7				
Official Product	HT Part No.T3A83UYG-60C000411U1930			
Tentative Product	********	*******		
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		01/30/2024	Version 1.2	Page 8/15



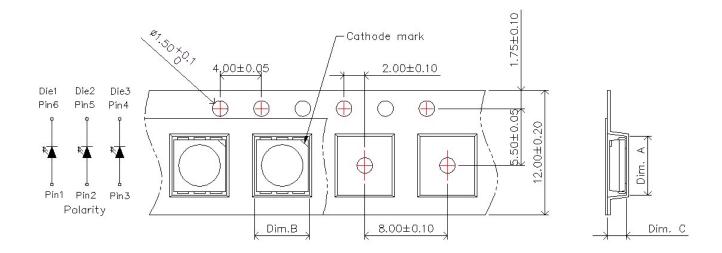
Precaution for Use

- 1. The chips should not be used directly in any type of fluid such as water, oil, organic solvent, etc.
- 2. When the LEDs are illuminating, the maximum ambient temperature should be first considered before operation.
- 3. LEDs must be stored in a clean environment. A sealed container with a nitrogen atmosphere is necessary if the storage period is over 3 months after shipping.
- 4. The LEDs must be used within 72 hrs after unpacked. Unused products must be repacked in an anti-electrostatic package, folded to close any opening and then stored in a dry and cool space.
- 5. The appearance and specifications of the products may be modified for improvement without further notice.
- 6. The LEDs are sensitive to the static electricity and surge. It is strongly recommended to use a grounded wrist band and anti-electrostatic glove when handling the LEDs. If a voltage over the absolute maximum rating is applied to LEDs, it will damage LEDs. Damaged LEDs will show some abnormal characteristics such as remarkable increase of leak current, lower turn-on voltage and getting unlit at low current.

Official Product	HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	********				
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		01/30/2024	Version 1.2	Page 9/15	

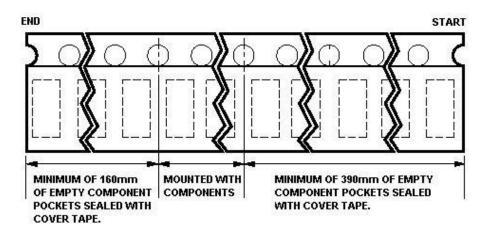


Packaging Tape Dimension



Dim. A	Dim. B	Dim. C	Qty/Reel
5.70±0.10	5.30±0.10	1.80±0.10	1K

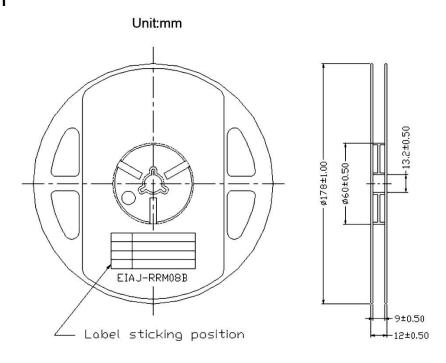
Unit: mm



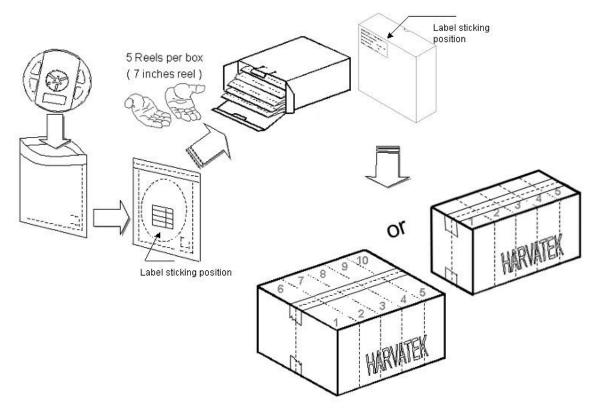
Official Product HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		01/30/2024	Version 1.2	Page 10/15



Reel Dimension



Packing



5 or 10 boxes per carton is available depending on shipment quantity.

Official Product	HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	********	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		01/30/2024	Version 1.2	Page 11/15	

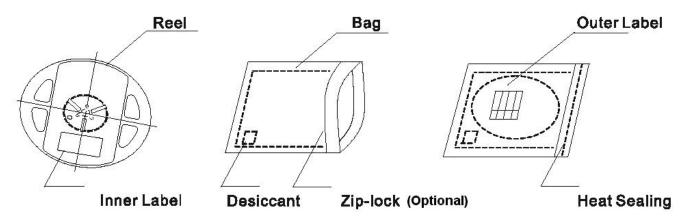


Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

A humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



Baking

Baking before soldering is recommended when the package has been unsealed for 72 hrs.

The conditions are as followings:

- 1. $60\pm3^{\circ}$ C ×(12~24hrs)and<5%RH, taped reel type.
- 2. $100\pm3^{\circ}$ C × (45min~1hr), bulk type.
- 3. $130\pm3^{\circ}$ C×(15min~30min), bulk type.

Precautions

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AlGaInP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

Official Product	HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	*******				
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		01/30/2024	Version 1.2	Page 12/15	



Handling of Silicone Resin LEDs

Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound.

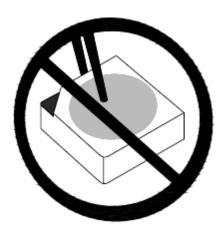


Figure 1

In general, LEDs should only be handled from the side. By the way ,this also applies to LEDs without a silicone sealant, since the surface can also become scratched.

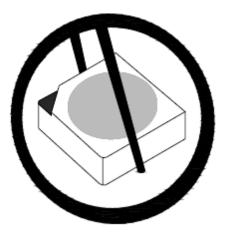


Figure 2

When populating boards in SMT production, there are basically no restrictions regarding the from of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented.

This is assured by choosing a pick and place nozzle which is large than LEDs reflector area.

Official Product	uct HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	********	******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		01/30/2024	Version 1.2	Page 13/15	

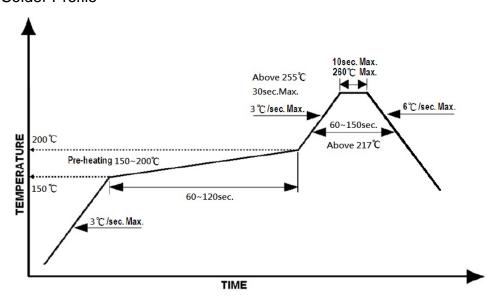


Reflow Soldering

Recommend soldering paste specifications:

- 1. Operating temp.: Above 217°C ,60~150 sec.
- 2. Peak temp.:260 ^OCMax.,10sec Max.
- 3. Reflow soldering should not be done more than two times.
- 4. Never attempt next process until the component is cooled down to room temperature after reflow.
- 5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

Lead-free Solder Profile



Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultrasonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

Official Product	t HT Part No.T3A83UYG-60C000411U1930				
Tentative Product	********	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		01/30/2024	Version 1.2	Page 14/15	



Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electric-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Revise History

Rev.	Descriptions	Date	Page
1.0		05/28/2021	-
1.1	Renew Form	08/30/2023	-
1.2	Renew Current 20 to 60	01/30/2024	ALL

Official Product HT Part No.T3A83UYG-60C000411U1930					
Tentative Product	********	********			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		01/30/2024	Version 1.2	Page 15/15	